

1                   DIE ATTACHMENT AND METHOD

2                   09/527,280

3                   ABSTRACT OF THE DISCLOSURE

4                 A method for forming a semiconductor device including a  
5                 die attach surface having a first pedestal and a first  
6                 semiconductor die having a first surface formed with a first  
7                 cavity for mounting the first semiconductor die on the first  
8                 pedestal. Further provision is made for the formation of a  
9                 dielectric cavity in the semiconductor die, the first  
10                pedestal or both. The cavity allows for fields produced by  
11                electronic components disposed on the upper surface of the  
12                semiconductor die to penetrate into the dielectric cavity.

13                Inclusion of a second pedestal on a common die attach  
14                surface and a second semiconductor die having second cavity  
15                for mounting provides for substantially coplanar precision  
16                alignment of the first and second semiconductor die.